



**Windows 11 Pro Fully Rugged Laptop with 14.0"  
Outdoor Display and Modular Expansion Areas...**

## **TOUGHBOOK 40 mk2 (AU & NZ spec only)**

The 14.0" fully-rugged Panasonic TOUGHBOOK 40 laptop breaks new ground offering unrivaled flexibility in even the most demanding and unpredictable environments, including Defence, Mining and Utilities. Incorporating a modular design with 8 expansion areas, the TOUGHBOOK 40 allows mobile workers to modify the device quickly and easily while in the field. The powerful rugged laptop is built for use in the most extreme conditions and designed for field specialists, incorporating quick release self-encrypting secure drives and providing up to 24 hours of battery life to support mission critical operations.

### **Key Features**

Windows 11 Pro

Intel® Core™ Ultra5 Processor 135H (with Intel vPro® Technology) or optional Intel® Core™ Ultra7 Processor 165H (with Intel vPro® Technology)\*

14.0" Active Matrix (TFT) colour LCD 1920 x 1080 (FHD) with sunlight-viewable glove-enabled capacitive touchscreen (up to 1,200cd/m<sup>2</sup> brightness)

Up to 180cm drop resistance\*\*\*, IP66 water and dust resistance, MIL-STD 810H certified\*\*\*

Long battery life of up to 12 hours (standard battery) or up to 24 hours with optional 2nd battery\*





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<https://oc.connect.panasonic.com/au/en/toughbook-40>

<b>Operating System</b>	Windows 11 Pro
<b>Mobile Computing Platform</b>	Intel® Core™ Ultra5 Processor 135H (with Intel vPro® Technology) or optional Intel® Core™ Ultra7 Processor 165H (with Intel vPro® Technology)*
<b>RAM</b>	Built-in 16GB RAM (max 64GB RAM*)
<b>Graphic Chip</b>	Intel® Graphics (Built-in CPU), support Intel® Arc™ Graphics when equipped with 2 RAM modules
<b>Storage</b>	Quick release 512GB NVMe OPAL SSD with heater (max 2TB). Optional 2nd SSD*
<b>LCD</b>	14.0" Active Matrix (TFT) colour LCD 1920 x 1080 (FHD) LCD with sunlight-viewable rain and glove-enabled capacitive touchscreen (up to 1,200cd/m <sup>2</sup> brightness)
<b>Bluetooth™</b>	5.3 Class 1
<b>Wireless LAN</b>	Intel® Wi-Fi7 BE200
<b>Mobile Broadband*</b>	4G LTE
<b>GPS*</b>	U-Blox NEO-M9N
<b>LAN</b>	IEEE 802.3 10Base-T / IEEE 802.3u 100BASE-TX / IEEE 802.3ab 1000BASE-T (optional 2nd GLAN*)
<b>Sound</b>	HD Audio Stereo Speakers
<b>Front Camera</b>	5MP with IR / privacy shutter (Windows Hello compliant)
<b>USB 3.2</b>	x2
<b>Thunderbolt 4</b>	x1
<b>Micro SDXC Memory Card</b>	x1
<b>HDMI</b>	x1
<b>Headset</b>	x1
<b>DC In</b>	x1
<b>Port Replicator</b>	x1
<b>Quad Path Through Connector</b>	x1
<b>Left Expansion Area**</b>	2nd SSD (NVMe), Smart Card Reader, DVD Multi Drive, Blu Ray Drive.
<b>Right Expansion Area**</b>	2nd Battery, Smart Card Reader.
<b>Palm Rest Expansion Area**</b>	Fingerprint reader (Windows Hello), Fingerprint reader (Windows Hello, Multi-user authentication), Contactless Smart Card Reader (HF-RFID).
<b>Rear Expansion Area**</b>	VGA + True Serial (RS232) + 2nd native GLAN or USB 3.2 Type A + True Serial (RS232) + 2nd HDMI or USB 3.2 Type A x2 + 2nd HDMI.
<b>AC Adapter</b>	Input: 100V - 240V AC, 50Hz/ 60Hz, Output: 15.6V DC, 7.05A
<b>Battery</b>	Lithium-Ion 10.8V, 6500mAh (typical), 6300mAh (minimum)
<b>Battery Life</b>	Approx 12 hours with standard battery (Mobile Mark™ 25) or up to 24 hours with optional 2nd battery* (Mobile Mark™ 25)
<b>Power Management</b>	Standby function, ACPI BIOS
<b>Dimensions (WxHxD)</b>	354mm x 301mm x 54.4mm (without protruding parts)
<b>Weight</b>	Approx 3.35kg (depending on configuration)
<b>Security</b>	TPM 2.0, Password security, Integrated hardware security lock slot
<b>Drop Resistance</b>	MIL-STD810H, 180cm***
<b>Dust Resistance</b>	IP6x
<b>Water Resistance</b>	IPx6
<b>Operating Temperature</b>	MIL-STD810H, -29°C to +63°C***
<b>Standard Configuration</b>	TOUGHBOOK 40 mk2, 16GB RAM, 512GB SSD, 1 x standard battery pack
<b>Included in the box</b>	Power Supply, Power Cord, Capacitive Stylus Pen, Tether, Display Cleaning Cloth and User Manual
<b>Footnote</b>	*Optional

\*\*One option exclusive possible in configuration port / business expansion module

\*\*\*Tested by an independent third party lab following MIL-STD810H Method 516.8 Procedure IV for transit drop test and Method 501.7 and 502.7 Procedure II for operation temperature test. May differ depending on models and options